

## Reutlingen wafer fab

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- ▶ Areas of operation
  - Manufacturing for semiconductors (Frontend)
  - Test center for semiconductors (Backend)
- ▶ Associates
  - about 4,000
- ▶ Cleanroom surface area
  - 35,000 m<sup>2</sup>, till end of 2025: 44,000 m<sup>2</sup>
- ▶ Production facilities
  - 150-millimeter technology since 1995
  - 200-millimeter technology since 2010
  - Pre- and final measurement for 150- and 200-millimeter wafers
- ▶ Manufactured products
  - Application-specific integrated circuits (ASICs), low-voltage/high-voltage power semiconductors, microelectromechanical systems (MEMS)
- ▶ Manufacturing technology
  - 150- and 200-millimeter silicon substrates with structural widths (nodes) of up to 180 nanometer
  - 150-millimeter silicon carbide substrates with structural widths (nodes) of up to 400 nanometer
- ▶ Fields of application for semiconductors
  - Power units for electromobility, e-bikes, power tools and further Bosch products
  - Automotive electronics: airbag and driver assistance systems, Electronic Stability Control ESC, electronic control units for electric motors and IC engines as well as for transmissions, parking assistants and night vision enhancement systems

Consumer electronics: games consoles,  
hearables, laptops, smartphones, wearables

## Investments and extension course of action

- ▶ Rising demand  
Consistent development of the manufacturing capacity to meet the growing demand of semi-conductors chips (ASICs, MEMS and power semiconductors).
  
- ▶ From 2021 to 2023  
With 150 million euros in two steps from 2021 to 2023 will gain about 4,000m<sup>2</sup> of new cleanroom surface area that will be realized in existing buildings. In addition, 150 new jobs in the fields of semiconductor development will be raised.
  
- ▶ Till end of 2025  
State-of-the-art manufacturing: more than 250 million euros will be invested for a new element, the total amount of the cleanroom surface area will raise up to 44,000 m<sup>2</sup>.